

STN[®]

Searching for patent families in DWPISM

FIZ Karlsruhe

STN

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Agenda

- What is a patent family?
- A practical example from the Derwent World Patents Index[®] (DWPISM) on STN[®]
- Search example
 - Using FSEARCH to find “Extended” patent families

What is a patent family?

- A list of the patent publications from around the world describing the same invention
- A list of patent publications that quote a common priority application number and date
- A method of summarizing the global legal protection being sought by a patent applicant
- A time saving convenience for both patent searchers and patent database producers

Patent family definitions

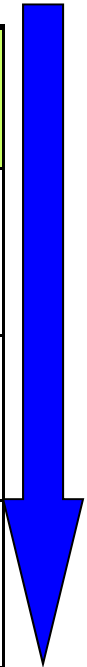
- **DWPI:** only documents whose priorities are in common with a **basic** publication
- **Extended:** all documents directly or indirectly linked via priorities (**FSEARCH**)

Basic = the patent family member selected for indexing and abstracting (usually the first published member).

A practical example

Publication order.

	<i>Publication</i>	<i>Priority 1</i>	<i>Priority 2</i>	<i>Priority 3</i>	<i>Priority 4</i>
1	US 20070246806 A1	US 2006-379332			
2	US 20090224391 A1		US 2008-42026		
3	US 20090236686 A1	US 2006-379332	US 2008-42026	US 2008-58175P	US 2009-476447



Three separate DWPI basic publications (records).

A practical example (cont.)

Publication order.

<i>Publication</i>	<i>Priority 1</i>	<i>Priority 2</i>	<i>Priority 3</i>	<i>Priority 4</i>
US 20070246806 A1	US 2006-379332			
US 20090224391 A1		US 2008-42026		
US 20090236686 A1	US 2006-379332	US 2008-42026	US 2008-58175P	US 2009-476447

1

One "Extended" patent family.

FSEARCH locates all related database records of an extended patent family

- FSEARCH iteratively searches Application (AP), Priority (PRN) and Publication (PN) Numbers to find all related database records
- Use the FSEARCH command to retrieve the “Extended” (broad) patent family in DWPI

Learn all about the FSEARCH command here:

<http://www.cas.org/training/stncommands/fsearch.html>

Use FSEARCH to locate the extended (broad) patent family in DWPI

```
=> FILE WPINDEX
```

```
=> S US20070246806/PN
```

```
L1          1 US20070246806/PN
```

```
=> FSEARCH L1
```

```
. . . .
```

```
*** ITERATION 3 ***
```

```
SEL L3 1- PN,APPS
```

```
L2          SEL L1 1- PN APPS : 7 TERMS
```

```
SEA L2
```

```
L3          3 L2
```

```
FSORT L3
```

```
L4          3 FSO L3
```

```
1 Multi-record Family      Answers 1-3
```

```
0 Individual Records
```

```
0 Non-patent Records
```

```
=> D L4 BIB 1-3
```

Here we are looking for the family of US20070246806 (L1).

FSEARCH retrieves the *extended patent family* in via iterative steps (L2 - L4).

In this example, the *extended family* is represented by three separate DWPI records (L4).

Use FSEARCH to locate the extended (broad) patent family in DWPI (cont.)

```
L4 ANSWER 1 OF 3 WPINDEX COPYRIGHT 2011 THOMSON REUTERS OR STN FAMILY 1
AN 2009-N89587 [65] WPINDEX
CR 2007-844114; 2009-N52782
TI Manufacturing method of semiconductor device, involves electrically
connecting interconnect structures that are formed on both surface of
encapsulant, after removing temporary carrier
DC T01; U11; U13; U24
IN CHOW S G; HUANG R; LIN Y; SHIM I K
PA (STAT-N) STATS CHIPPAC LTD
CYC 1
PIA US 20090236686 A1 20090924 (200965)* EN 18[7]
ADT US 20090236686 A1 US 2009-476447 20090602; US 20090236686 A1
Provisional US 2008-58175P 20080602; US 20090236686 A1 CIP of US
2008-42026 20080304; US 20090236686 A1 CIP of US 2006-379332 20060419
PRAI US 2009-476447 20090602
US 2008-58175P 20080602
US 2008-42026 20080304
US 2006-379332 20060419
```

The related DWPI records are also cross-referenced (CR) by Accession Number (AN).

Use FSEARCH to locate the extended (broad) patent family in DWPI (cont.)

L4 ANSWER 2 OF 3 WPINDEX COPYRIGHT 2011 THOMSON REUTERS on STN FAMILY 1

AN 2009-N52782 [61] WPINDEX

CR 2007-844114; 2009-N89587

TI Method of manufacturing semiconductor device e.g. wafer-level semiconductor package for industrial and commercial electronic equipment, involves forming interconnect structure. . . .

DC U11

IN CAO H; LIN Y

PA (STAT-N) STATS CHIPPAC LTD

CYC 1

PIA US 20090224391 A1 20090910 (200961)* EN 22[12]

ADT US 20090224391 A1 US 2008-42026 20080304

PRAI US 2008-42026 20080304

L4 ANSWER 3 OF 3 WPINDEX COPYRIGHT 2011 THOMSON REUTERS on STN FAMILY 1

AN 2007-844114 [78] WPINDEX

CR 2009-N52782; 2009-N89587

TI Embedded integrated circuit package system useful in electronics, comprises substrate forming encapsulation to cover integrated circuit die and conductive pattern; and channel with conductive material. . . .

DC U11; V04

IN CHOW S G; MERILO D A; ONG Y Y

PA (STAT-N) STATS CHIPPAC LTD

CYC 1

PIA **US 20070246806** A1 20071025 (200778)* EN 14[16]

ADT US 20070246806 A1 US 2006-379332 20060419

PRAI US 2006-379332 20060419

The DWPI record for US20070246806.

Resources

- DWPI on STN User Documentation
 - http://www.stn-international.com/stn_dwpi.html
 - DWPI on STN Reference Manual
 - DWPI on STN Workshop Manual
 - DWPI Classification (DC) guide
 - Summary table of member level data coverage
 - Global Patent Sources – DWPI coverage in detail
 - Chemistry, Engineering and Polymer User Guides
- DWPI on STN database summary sheet
 - <http://www.stn-international.com/wpindex.html>

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For more information ...

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